

International Application No.: PCT/JP2004/008875
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IN THE ABSTRACT:

Please replace the Abstract of the Disclosure originally filed with the above-identified patent application with the following Abstract:

ABSTRACT OF THE DISCLOSURE

A three-dimensional component (4)—having cavities (18)—containing a photocurable resin material (10)—and having a structure in which a plurality of cured resin layers (17)—composed of the photo-cured resin material (10)—are stacked, is manufactured by stereolithography. Inorganic members (2)—are inserted into concave portions (20)—when the concave portions (20)—are formed before covering the cavities (18), each of the concave portions being at least part a portion of the corresponding cavity—(18), and the photocurable resin material (10)—remaining. When the three-dimensional component (4)—is completed, the photocurable resin material (10)—remaining in the cavity (18)—is thermally cured, thus being brought into ~~intimate~~ contact with the inorganic members—(2). In this waymanner, a three-dimensional photonic structure (1)—having the plurality of inorganic members (2)—precisely disposed at desired periodic positions within the resin matrix (3)—~~can be~~is efficiently manufactured.